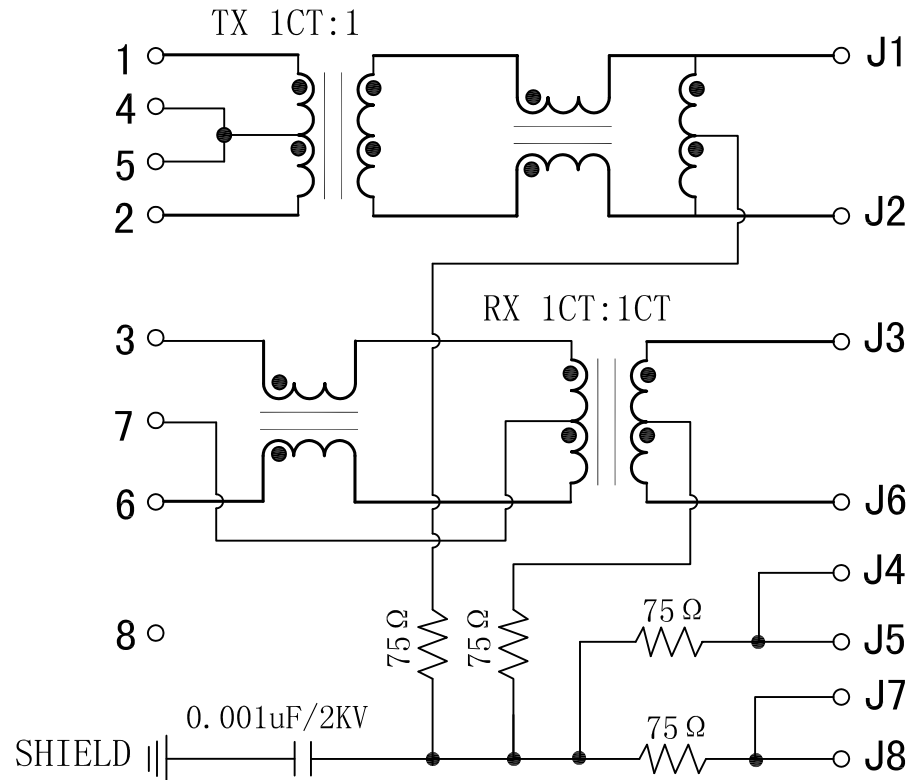


# Schematic:

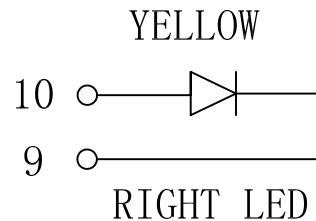
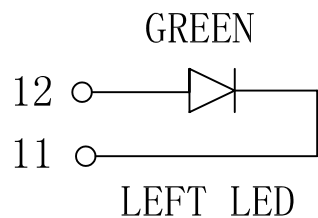
REV.	ECN NO.	DESCRIPTION	DATE	APPD
B	REL		2010/05/18	



## Electrical Specifications:

TEST NOTES (25±5°C)

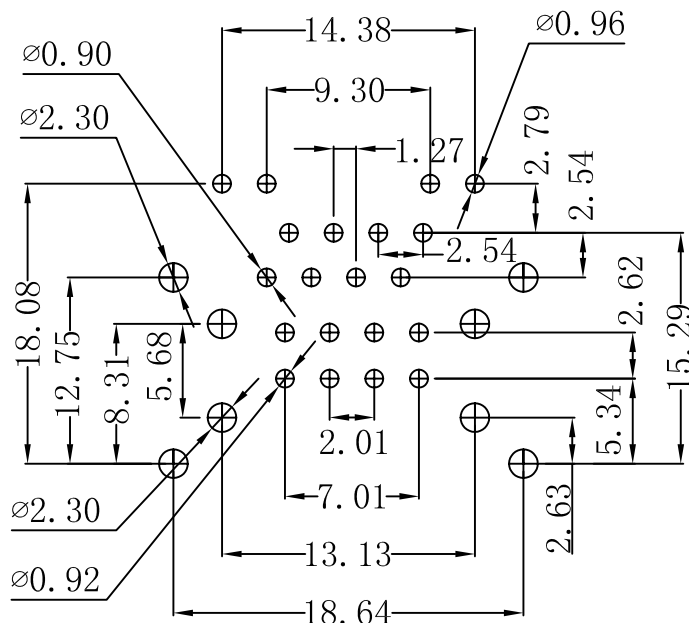
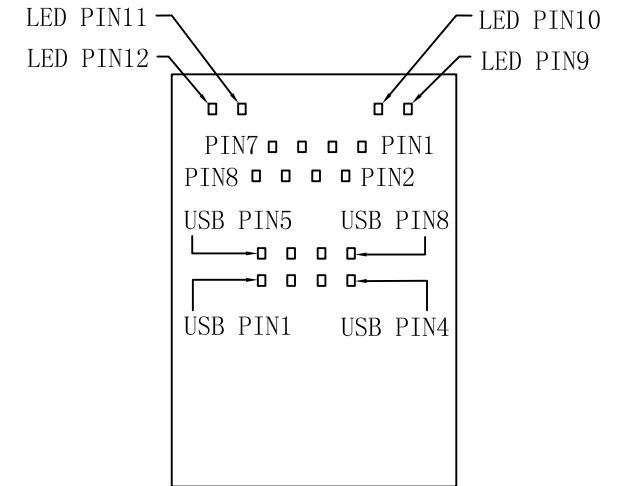
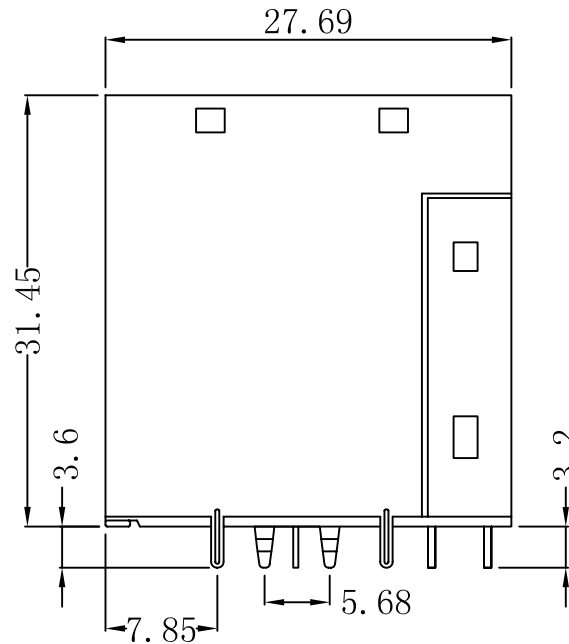
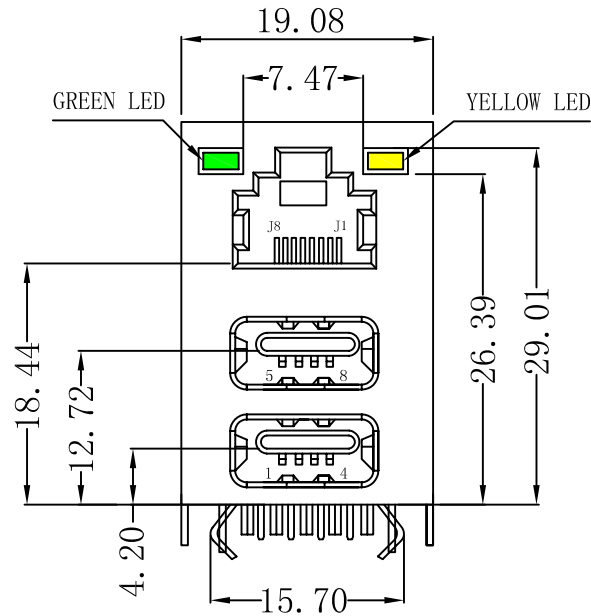
- TR: (100KHz, 0.1V);  
TX=1CT:1 ±2%  
RX=1CT:1CT ±2%
- LX: (100KHz, 100mV, 8mA, DC Bias)  
PINS: (P1, P2), (P3, P6)=350uH MIN
- HIPOT:  
1500VAC FOR 60 SECONDS
- INSERTION LOSS:  
-1.0dB MAX @ 1.0MHz TO 100MHz
- RETURN LOSS:  
-18dB MIN @ 1MHz TO 30MHz  
-16dB MIN @ 30MHz TO 60MHz  
-12dB MIN @ 60MHz TO 80MHz
- CROSS TALK:  
-40dB MIN @1MHz TO 10MHz  
-35dB MIN @32MHz TO 60MHz  
-30dB MIN @60MHz TO 100MHz
- COMMON TO COMMON MODE REJECTION:  
-30dB MIN @1MHz TO 50MHz  
-20dB MIN @50MHz TO 150MHz
- OPERATING TEMPERATURE: -40°C ~ +85°C.



X:X	±0.20	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED	
X:XX	±0.10	CHKD:		
X:XXX	±0.05	DR: TOM	TITLE: RJ45 10/100 Base-TX Jack/ Dual USB Combo	
ANGLES	±1°	UNIT: mm	PART NO.: LPJU5404BHNL	
	SCALE: 2/1	SHEET: 2/2	REV: B	DWG NO.: LP10051801

# Mechanical:

REV.	ECN NO.	DESCRIPTION	DATE	APPD
B	REL		2010/05/18	



SUGGESTED PCB LAYOUT (TOP VIEW)



## NOTES:

1. Designed to support application, such as SOHO (ADSL modems), LAN-on-Motherboard (LOM), hub and Switches.
2. Meets IEEE 802.3 specification
3. Connector Materials:  
 Housing: Thermoplastic UL94V-0  
 Contact/Shield: Copper alloy  
 Shield plating: Nickel  
 RJ-45 Contact plating: Gold 6 micro-inches min. In contact area  
 USB Contact plating: Gold Flash.
4. Wave peak temperature: 260°C, 5Sec.

X:X	$\pm 0.20$	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED
X:XX	$\pm 0.10$	CHKD:	
X:XXX	$\pm 0.05$	DR: TOM	TITLE: RJ45 10/100 Base-TX Jack/ Dual USB Combo
ANGLES	$\pm 1^\circ$	UNIT: mm	PART NO.: LPJU5404BHNL
	SCALE: 2/1	SHEET: 1/2	REV: B DWG NO.: LP10051801